



PATENT
Customer No. 22,852
Attorney Docket No. 04329.2230

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kenji HASHIMOTO

Application No.: 09/503,170

Filed: February 14, 2000

For: RESIN ENCAPSULATING
APPARATUS AND METHOD
USED IN A MANUFACTURE OF A
SEMICONDUCTOR DEVICE

Group Art Unit: 1722

Examiner: R. Davis

#8/B
fee on

Commissioner for Patents
Washington, DC 20231

RECEIVED
JUL 18 2002
TC 1700

Sir:

AMENDMENT

In reply to the Office Action dated April 10, 2002, please amend the application
as follows:

IN THE CLAIMS:

Please amend claims 1 and 8, and add new claims 21-26, as follows:

1. (Amended) A resin encapsulating apparatus comprising:

a retaining section which retains a semiconductor device;

a mask set on the semiconductor device and having an opening at which part of

the semiconductor device is exposed;

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